

USP KERAFOL®

Thermal Management – KERAMOLD®



What makes our KERAMOLD® successful?

- Processable by extrusion, injection molding or 3D printing
- Overmolding of electrical components or production of 3-dimensional tailor-made gap-pads
- High thermal conductivity and electrical insulation
- Protection of electrical components (dust, moisture, water, etc)
- Fast production cycle / rapid fabrication speed (compared to GFL or potting materials)
- 3D heat transfer
- Compensation of height differences for higher heat transfer
- Adjustable material properties

